



NS□161/163 Series

Numeric Display/Case Size 12.5 x 17.0 mm

Features

Case Size	12.5 x 17.0 mm (W x H)
Product features	• A black case and a gray case are available. • Lead-free soldering compatible • RoHS compliant
Peak wavelength	Green : 565nm Orange : 605nm Red : 660nm
Number of Digit	1 Digit
Segment Shape	Arrow Feather Type
Character Height	13.6 mm
Die materials	Green : GaP Orange : GaAsP Red : GaAlAs
Soldering methods	TTW (Through The Wave) soldering and manual soldering
ESD	More than 2kV(HBM)
Packing	Tray

Recommended Applications

Amusement Equipment, Electric Household Appliances, Other General Applications

Emitted Color

Part No.		Material	Emitted Color	Chip/ Segment
Case Color Black	Case Color Gray			
NSG161P-B	NSG163P-B	GaP	Green	1
NSA161-B	NSA163-B	GaAsP	Orange	1
NSR161-B	NSR163-B	GaAlAs	Red	1
NSR161-C	NSR163-C	GaAlAs	Red	1

Absolute Maximum Ratings

(Ta=25°C)

Item	Symbol	Absolute Maximum Ratings			Unit
		Green	Orange	Red	
Power Dissipation	Pd	63	63	60	mW/seg
Forward Current	I _F	25	25	30	mA/seg
Pulse Forward Current ※1	I _{FRM}	100	100	120	mA/seg
Derating (Ta=25°C or higher)	ΔI _F	0.34	0.34	0.41	mA/°C
	ΔI _{FRM}	1.35	1.35	1.64	mA/°C
Reverse Voltage	V _R	4	4	4	V
Operating Temperature	T _{opr}	-40~+85	-40~+85	-40~+85	°C
Storage Temperature	T _{stg}	-40~+85	-40~+85	-40~+85	°C

 ※1 I_{FRM} Measurement condition : Duty 1/5, f = 1kHz

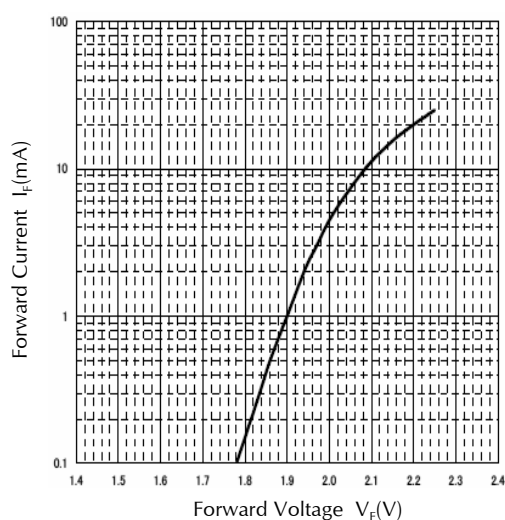
Electro-Optical Characteristics

(Ta=25°C)

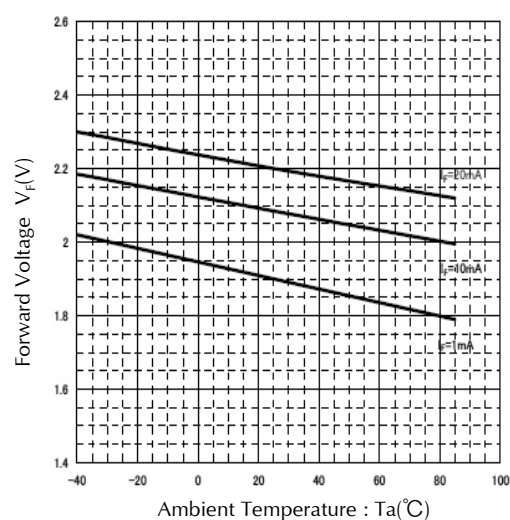
Item	Conditions	Symbol		Characteristics			Unit
				Green	Orange	Red	
Luminous Intensity (-B Product)	I _F =20mA	I _V	MIN.	2	4	6	mcd/seg
			TYP.	4	8	12	
Luminous Intensity (-C Product)	I _F =20mA	I _V	MIN.	-	-	12	mcd/seg
			TYP.	-	-	15	
Forward Voltage	I _F =20mA	V _F	TYP.	2.2	2.2	1.7	V/seg
			MAX.	2.5	2.5	2.0	
Reverse Current	V _R =4V	I _R	MAX.	100	100	100	μA/seg
Peak Wavelength	I _F =20mA	λ _p	TYP.	565	605	660	nm
Spectral Line Half Width	I _F =20mA	Δλ	TYP.	30	30	30	nm

Technical Data(Green)

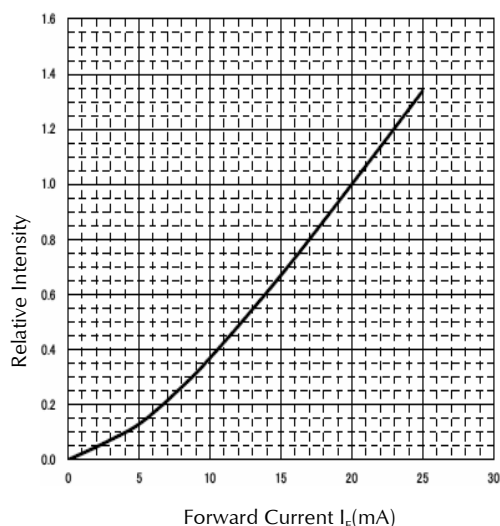
Forward Voltage vs. Forward Current
Condition : $T_a = 25^\circ\text{C}$



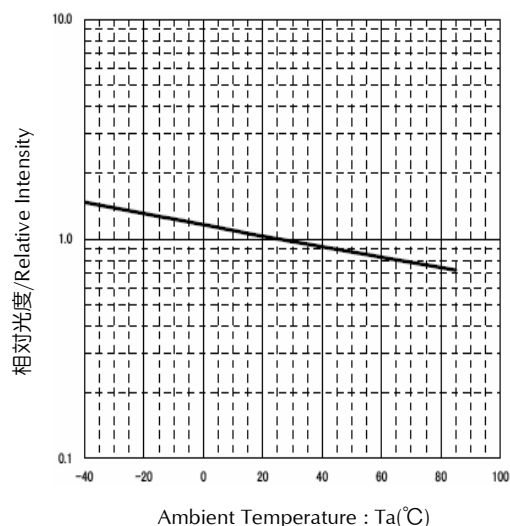
Ambient Temperature vs. Forward Voltage



Forward Current vs. Relative Intensity
Condition : $T_a = 25^\circ\text{C}$

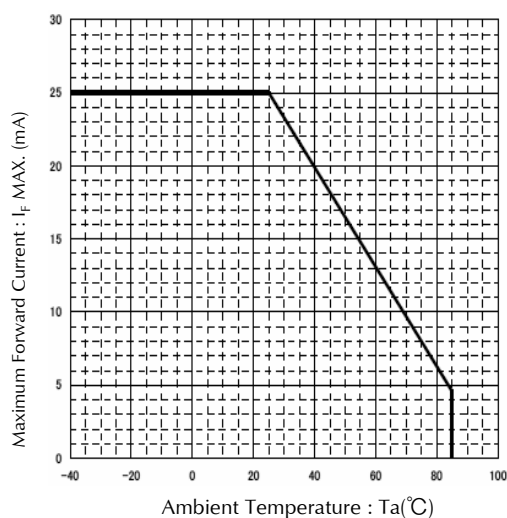


Ambient Temperature vs. Relative Intensity
Condition : $I_F = 20\text{mA}$

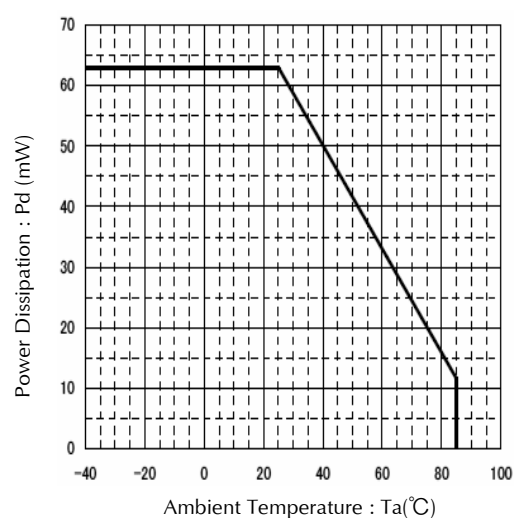


Technical Data(Green)

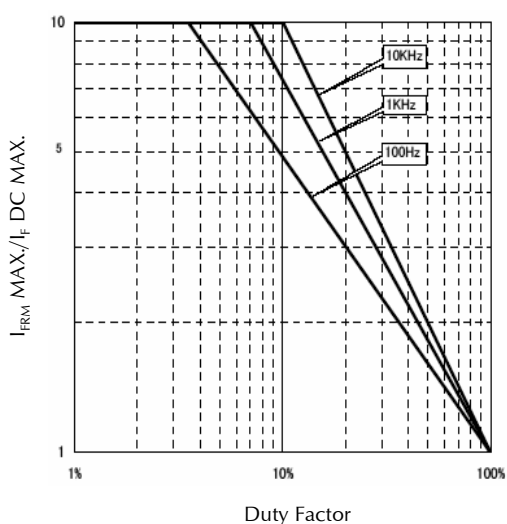
Ambient Temperature vs. Maximum Forward Current



Ambient Temperature vs. Power Dissipation

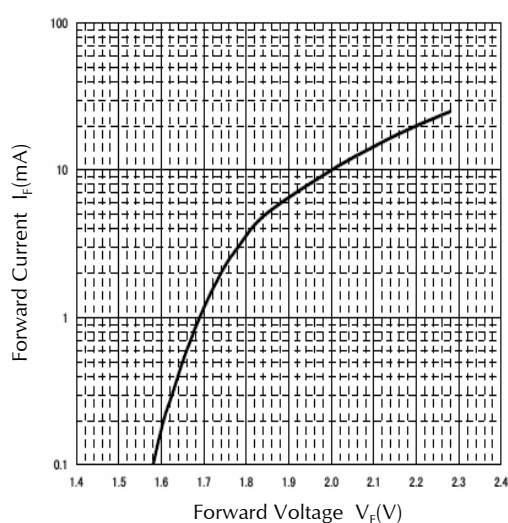


Duty Factor vs. Maximum Tolerable Pulse Forward Current
Condition: $T_a = 25^\circ\text{C}$

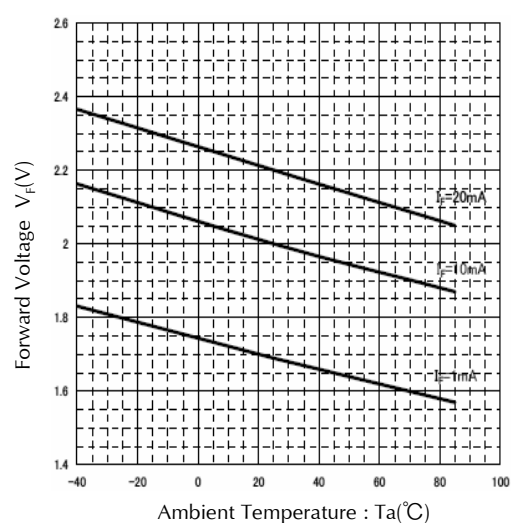


Technical Data(Orange)

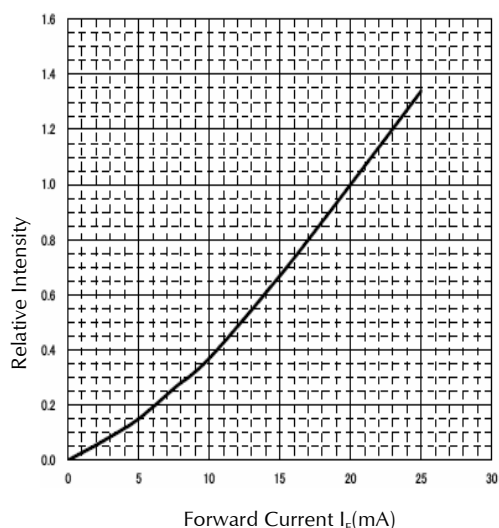
Forward Voltage vs. Forward Current
Condition : $T_a = 25^\circ\text{C}$



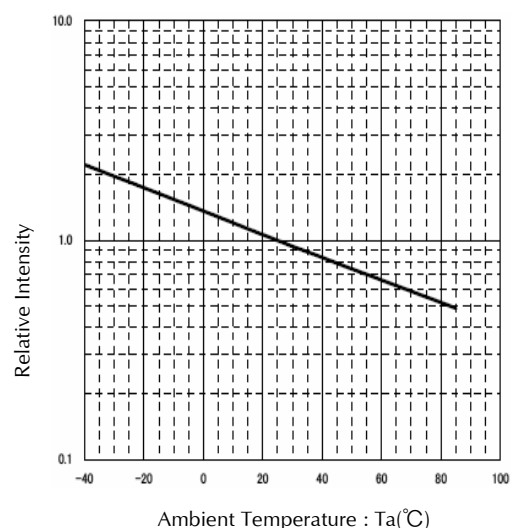
Ambient Temperature vs. Forward Voltage



Forward Current vs. Relative Intensity
Condition : $T_a = 25^\circ\text{C}$

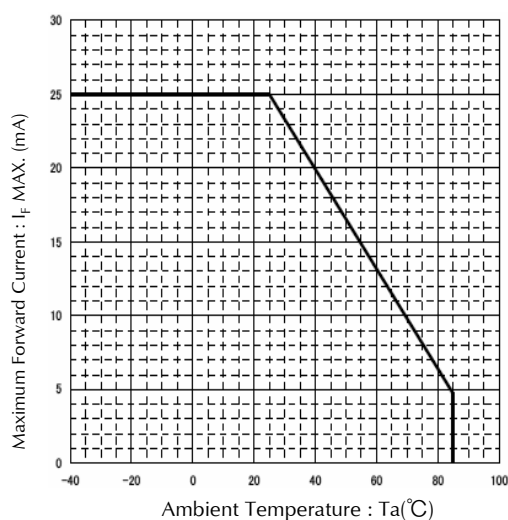


Ambient Temperature vs. Relative Intensity
Condition : $I_F = 20\text{mA}$

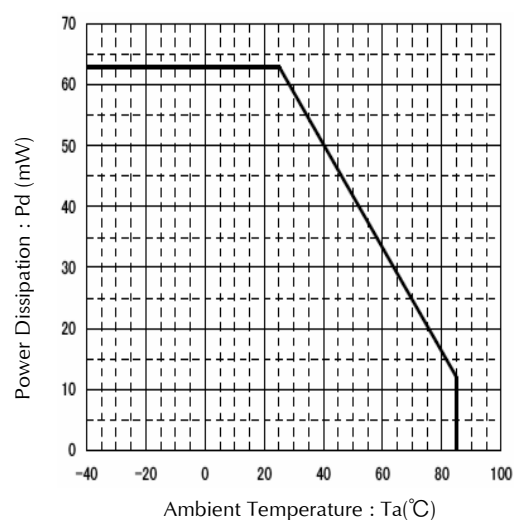


Technical Data(Orange)

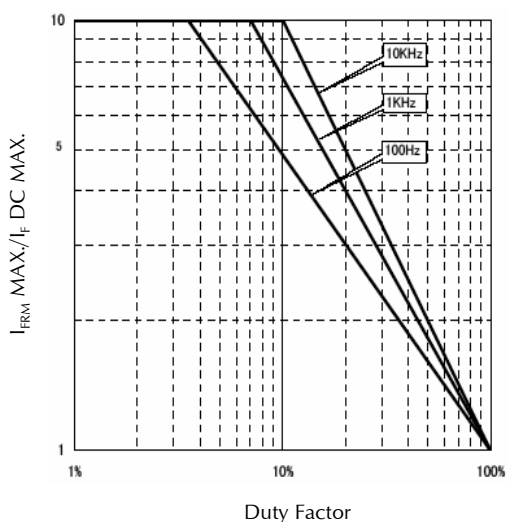
Ambient Temperature vs. Maximum Forward Current



Ambient Temperature vs. Power Dissipation

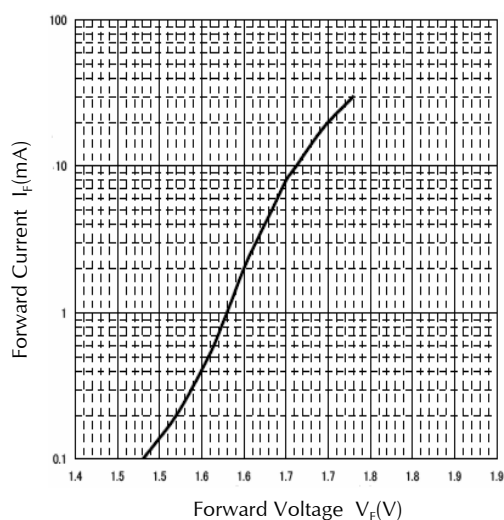


Duty Factor vs. Maximum Tolerable Pulse Forward Current
Condition : $T_a = 25^\circ\text{C}$

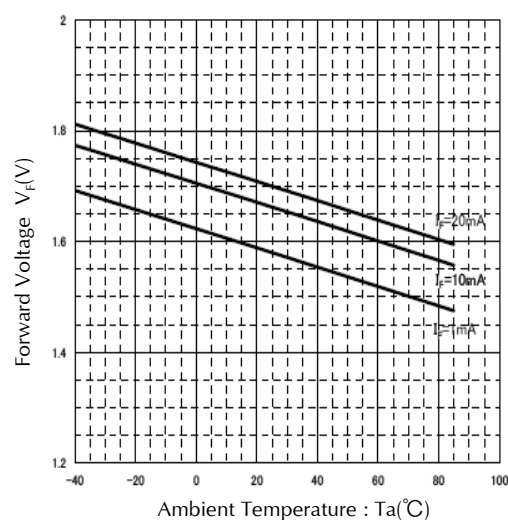


Technical Data(Red)

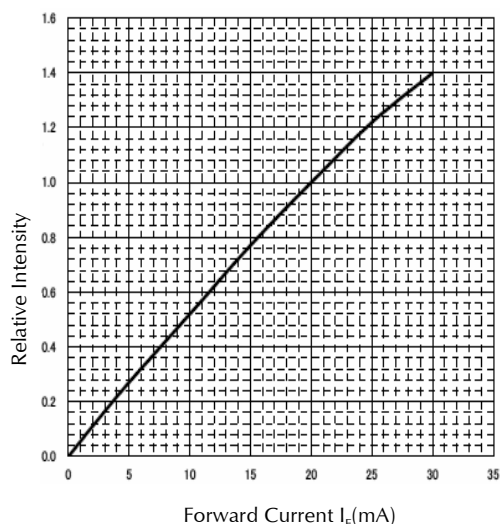
Forward Voltage vs. Forward Current
Condition : $T_a = 25^\circ\text{C}$



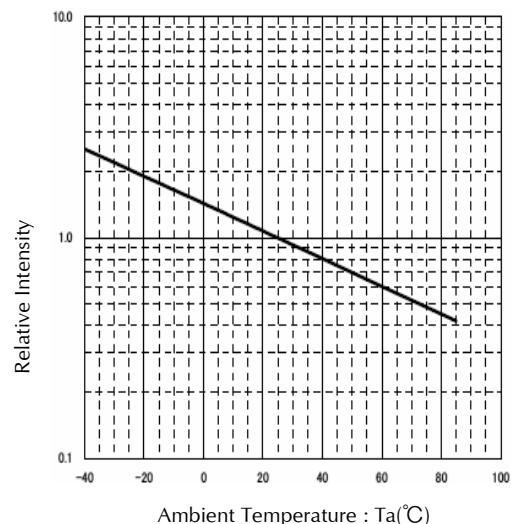
Ambient Temperature vs. Forward Voltage



Forward Current vs. Relative Intensity
Condition : $T_a = 25^\circ\text{C}$

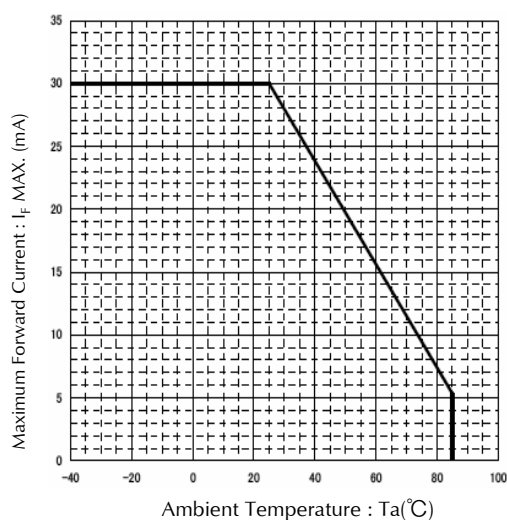


Ambient Temperature vs. Relative Intensity
Condition : $I_F = 20\text{mA}$

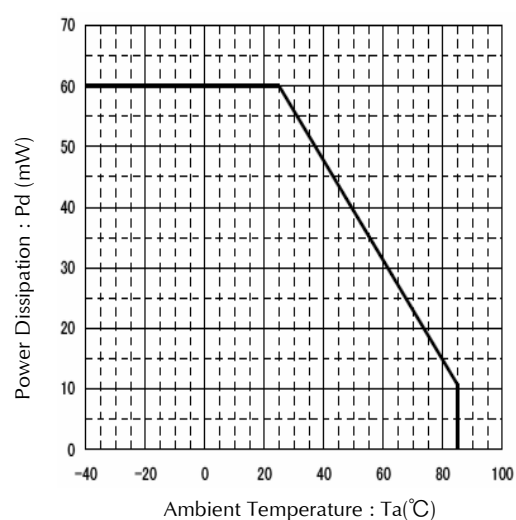


Technical Data(Red)

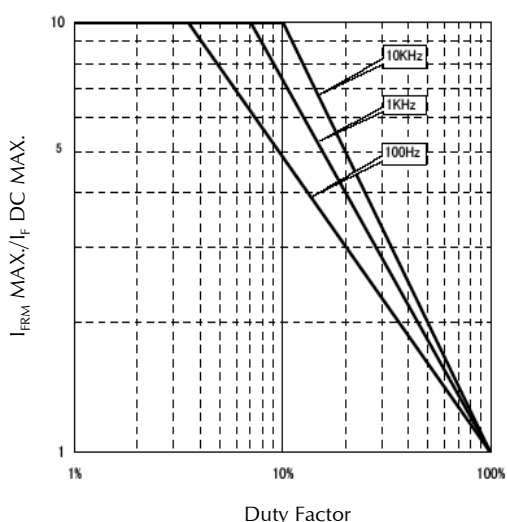
Ambient Temperature vs. Maximum Forward Current



Ambient Temperature vs. Power Dissipation



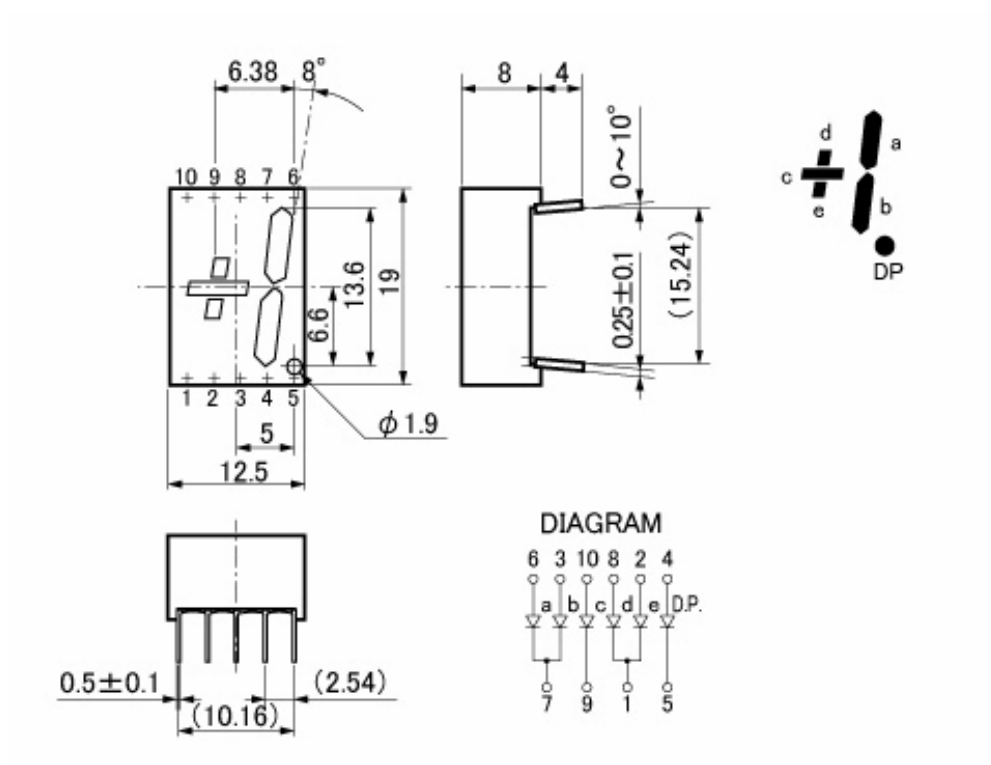
Duty Factor vs. Maximum Tolerable Pulse Forward Current
Condition : $T_a = 25^\circ\text{C}$



Package Dimensions

(Unit: mm)

(Tolerance : ± 0.25 mm)



TTW (Through The Wave) soldering Conditions

Pre-heating	100 °C 60 s	(MAX.) Resin surface temperature (MAX.)
Solder Bath Temp.	265 °C	(MAX.)
Dipping Time	5 s	(MAX.)
Position	At least 2.0 mm away from resin body	

- 1) The dip soldering process shall be 2 times maximum.
- 2) The product shall be cooled to normal temperature before the second dipping process.

Manual Soldering Conditions

Iron tip temp.	400 °C	(MAX.) (30 W Max.)
Soldering time and frequency	3 s 2 times	(MAX.) (MAX.)
Position	At least 2.0 mm away from resin body	

Reliability Testing Result

Reliability Testing Result	Applicable Standard	Testing Conditions	Duration	Failure
Room Temp. Operating Life	EIAJ ED-4701/100(101)	Ta = 25°C, If = Maximum Rated Current/seg	1,000 h	0/10
Resistance to Soldering Heat	EIAJ ED-4701/300(302)	260±5°C, 3mm from package base	10s	0/10
Temperature Cycling	EIAJ ED-4701/100(105)	Minimum Rated Storage Temperature(30min) ~Normal Temperature(15min) ~Maximum Rated Storage Temperature(30min) ~Normal Temperature(15min)	5 cycles	0/10
Wet High Temp. Storage Life	EIAJ ED-4701/100(103)	Ta = 60±2°C, RH = 90±5%	1,000 h	0/10
High Temp. Storage Life	EIAJ ED-4701/200(201)	Ta = Maximum Rated Storage Temperature	1,000 h	0/10
Low Temp. Storage Life	EIAJ ED-4701/200(202)	Ta = Minimum Rated Storage Temperature	1,000 h	0/10
Lead Tension	EIAJ ED-4701/400(401)	5N, 1time	10s	0/10
Vibration, Variable Frequency	EIAJ ED-4701/400(403)	98.1m/s ² (10G), 100 ~ 2KHz sweep for 20min., XYZ each direction	2 h	0/10
Lead Bend	EIAJ ED-4701/400(401)	2.5N, 0° ↔ 90°	2 times	0/10
Shock	JIS C 7201 A-8	It falls on wood engraving from height of 75cm.	3 times	0/10

Failure Criteria

Items	Symbols	Conditions	Failure criteria
Luminous Intensity	Iv	If Value of each product Luminous Intensity	Testing Min. Value < Spec. Min. Value x 0.5
Forward Voltage	V _F	If Value of each product Forward Voltage	Testing Max. Value ≥ Spec. Max. Value x 1.2
Reverse Current	I _R	V _R = Maximum Rated Reverse Voltage V	Testing Max. Value ≥ Spec. Max. Value x 2.5
Cosmetic Appearance	-	-	No notable, decoloration, deformation and cracking

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